



Material Content Data Sheet



Sales Product Name		2EDL05N06PJ		Issued		25. September 2017		
MA#		MA001330726						
Package		PG-DSO-14-49		Weight*		138.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.952	0.69	0.69	6858	6858
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		103	
	non noble metal	zinc	7440-66-6	0.057	0.04		414	
	non noble metal	iron	7439-89-6	1.150	0.83		8280	
wire	non noble metal	copper	7440-50-8	46.675	33.62	34.50	336193	344990
	noble metal	gold	7440-57-5	0.229	0.16	0.16	1646	1646
	encapsulation	organic material	carbon black	1333-86-4	0.175	0.13		1263
encapsulation	plastics	epoxy resin	-	9.470	6.82		68208	
	inorganic material	silicondioxide	60676-86-0	78.036	56.21	63.16	562090	631561
leadfinish	non noble metal	tin	7440-31-5	1.226	0.88	0.88	8832	8832
plating	noble metal	silver	7440-22-4	0.307	0.22	0.22	2208	2208
glue	plastics	acrylic resin	-	0.119	0.09		859	
	noble metal	silver	7440-22-4	0.423	0.30	0.39	3046	3905
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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